

Title (en)

DEVICE FOR ELECTRICALLY TESTING THE INTERCONNECTIONS OF A MICROELECTRONIC DEVICE

Title (de)

VORRICHTUNG ZUR ELEKTRISCHEN PRÜFUNG VON VERBINDUNGEN EINER MIKROELEKTRONISCHEN VORRICHTUNG

Title (fr)

DISPOSITIF DE TEST ELECTRIQUE D'INTERCONNEXIONS D'UN DISPOSITIF MICROELECTRONIQUE

Publication

EP 2873093 A1 20150520 (FR)

Application

EP 13736567 A 20130711

Priority

- FR 1256689 A 20120711
- EP 2013064677 W 20130711

Abstract (en)

[origin: WO2014009470A1] The present application provides a device for the simultaneous electrical testing of TSV interconnection elements (107) passing through a substrate (100), comprising one end connected to a integrated testing circuit and another end that has a removable connection means (115) assembled to the substrate by means of an anisotropic conductive adhesive.

IPC 8 full level

H01L 21/66 (2006.01)

CPC (source: EP US)

G01R 1/20 (2013.01 - US); **G01R 31/2853** (2013.01 - EP US); **H01L 22/14** (2013.01 - EP US); **H01L 22/34** (2013.01 - EP US);
H01L 2924/0002 (2013.01 - EP US)

Citation (search report)

See references of WO 2014009470A1

Citation (examination)

US 2010295600 A1 20101125 - KIM JONGHAE [US], et al

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

WO 2014009470 A1 20140116; EP 2873093 A1 20150520; FR 2993396 A1 20140117; FR 2993396 B1 20150515; US 2015115973 A1 20150430;
US 9784786 B2 20171010

DOCDB simple family (application)

EP 2013064677 W 20130711; EP 13736567 A 20130711; FR 1256689 A 20120711; US 201314399302 A 20130711